

2022-05-29 S STEM KONTROL 2024/03-08  
ÜRET M MURAT IRKAN 2024  
TAR H: HIZ:7.8Gbps ÜÇ BAND Wi-Fi  
6/6E- ROUTER

**MEDIATEK**

*everyday genius*

## MT7986A Datasheet for BPI-R3

Version: 1.15  
Release date: 2022-05-29

## Overview

**MT7986A** is a highly integrated wireless network router system-on-chip used for high wireless performance, home entertainment, and home automation and so on.

MT7986A is fabricated with advanced silicon process and integrates a Quad-core ARM® Cortex-A53 MPCore™ operating up to 2.0GHz and more DRAM bandwidth. This SoC also includes a variety of peripherals, including one USB3.0/USB2.0 (Host), one USB2.0 (Host), and one PCIe2.0 2lane (RC) ports. To support popular network applications, MT7986A also implements two 2.5Gbps HSGMII Ethernet interface. MT7986A combines with two RF chips, they can provide dual-band concurrent chipset solution for WIFI6E AX6000 wireless router platform. User also can create tri-band solution by connecting wireless NIC card thru its PCIe port.

Besides the connectivity features, the hardware-based NAT engine with QoS embedded in MT7986A transporting the audio/video streams in higher priority than other non-timely services also enriches the home entertainment application. The SFQ separating P2P sessions from audio/video ones so that MT7986A guarantees the streaming service.

With the advanced technology and abundant features, MT7986A is well positioned to be the core of next-generation Smart WiFi AP router, and home gateway systems.

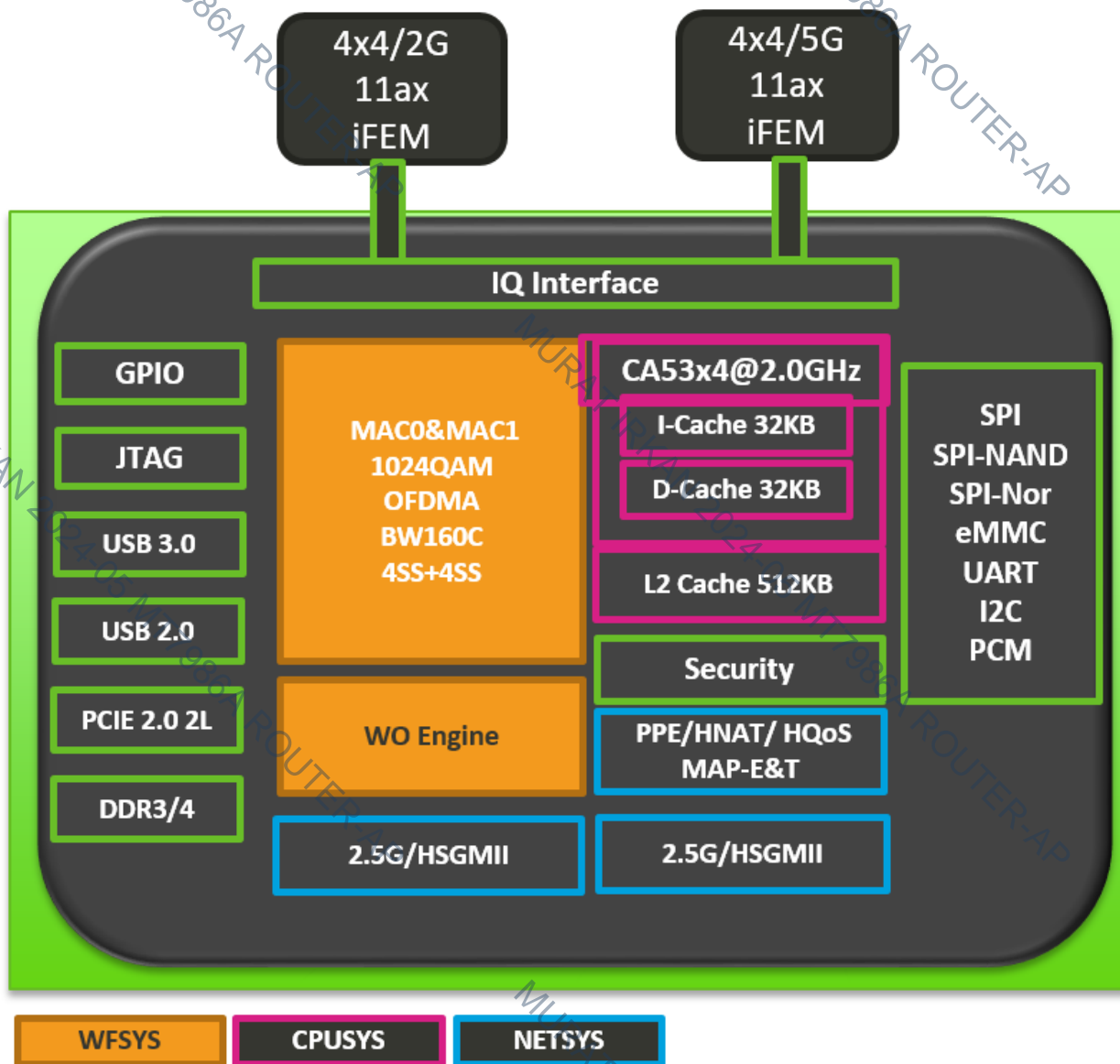
### Applications:

- Internet Service Router
- Wireless Router
- Wireless Repeater
- Home Security Gateway
- Home Automation
- NAS Devices

## Key Features

- Embedded Quad-core ARM® Cortex-A53 MPCore operating at 2.0GHz
  - 32KB L1 I-Cache and 32KB L1 D-Cache
  - 512KB unified L2 Cache
  - NEON/FPU
- Discrete 16-bit DDR3/4 chip
- NOR (SPI), NAND Flash (SPI, SLC), eMMC5.1
- USB3.0/USB2.0 Host x1
- USB2.0 Host x1
- PCIe2.0 2-lane HOST x1
- Audio PCM interface x1
- SPI, I2C, UART Lite, JTAG, MDC, MDIO, GPIO, PWM
- Two HSGMII(2.5Gbps) interfaces
- WiFi
  - Lead in 4x4+4x4 WIFI6E integration
  - Airtime Fairness
  - Spectrum Analyzer
- HW NAT
  - Ethernet/WiFi
  - Wired speed
  - IPv4 routing, NAT, NAPT
  - IPv6 routing, DS-Lite, 6RD
- HW QoS
  - 128 hardware queues to guarantee the min/max bandwidth of each flow.
  - Seamlessly co-work with HW NAT engine.
  - SFQ w/ 1k queues.
- Security
  - Secure boot
  - Crypto Suite
  - Anti Clone
- Green
  - Intelligent Clock Scaling (exclusive)
  - DDR: ODT off, Self-refresh mode

**Functional Block Diagram**



## Document Revision History

---

V1.15

## Table of Contents

Overview .....	2
Key Features.....	2
Functional Block Diagram.....	3
Document Revision History.....	4
Table of Contents.....	5
<b>1 General Features .....</b>	<b>7</b>
1.1 Platform Features .....	7
1.2 Wireless Connectivity Features.....	8
1.2.1 Wi-Fi MAC .....	8
1.2.2 WLAN Baseband.....	8
1.3 Wired Ethernet Features .....	9
1.4 Main Features Summary .....	10
<b>2 Pin .....</b>	<b>11</b>
2.1 Pin Sharing Schemes .....	12
2.1.1 Pin share scheme.....	12
2.2 Strapping Options.....	15
<b>3 Electrical Characteristics .....</b>	<b>16</b>
3.1 Absolute Maximum Ratings.....	16
3.2 Recommended Operating Range.....	17
3.3 Thermal Characteristics.....	18
3.4 Current Consumption .....	18
3.5 Storage Conditions.....	18
3.6 AC Electrical Characteristics .....	19
3.6.1 UART Interface.....	19
3.6.2 SPI Interface.....	19
3.6.3 SMI Interface .....	20
3.6.4 WRI Interface .....	21
3.6.5 I2C Interface.....	21
3.7 DC Electrical Characteristics .....	22
3.7.1 3.3V IO .....	22
3.7.2 1.8V IO .....	22

## Lists of Tables and Figures

Table 1-1 Main Features .....	10
Table 2-5 Pin Share .....	12
Table 2-6 Strapping .....	15
Table 3-1 Absolute Maximum Ratings .....	16
Table 3-2 Recommended Operating Range .....	17
Table 3-3 Thermal Characteristics .....	18
Table 3-4 SPI Master Electrical Specifications .....	20
Table 3-5 SMI Interface Diagram Key .....	21
Table 3-6 WRI Interface Diagram Key .....	21
Table 3-7 I2C Interface Diagram Key .....	21
Table 3-8 3.3V IO Electrical Characteristics .....	22
Table 3-9 1.8V IO Electrical Characteristics .....	22
Figure 3-1 UART Timing .....	19
Figure 3-2 SPI Master Timing Diagrams .....	19
Figure 3-3 SMI MDIO Timing .....	20
Figure 3-4 WRI Timing .....	21
Figure 3-5 I2C Timing .....	21

## 1 General Features

### 1.1 Platform Features

- **AP MCU subsystem**

- Quad-core ARM® Cortex-A53 MPCore™ operating at 2.0 GHz
- NEON processing engine with Advanced SIMD and Floating-point Extension
- 32KB L1 I-cache and 32KB L1 D-cache
- 512KB unified L2 cache
- Cryptography Extension

- **WiFi MCU subsystem**

- Andes processor with I/D cache

- **Memory interface**

- Supports discrete DDR3/4 chip
- 16-bit data bus width
- Memory speed up to DDR3-2133 and DDR4-3200
- Supports self-refresh/partial self-refresh mode
- Programmable slew rate for memory controller's IO pads
- Advanced bandwidth arbitration control

- **External interface**

- 1 USB3.0/USB2.0 (Host)
- 1 USB2.0 (Host)
- 1 PCIe2.0 2lane (Host)
- UART for external devices and debugging interfaces
- SPI master for external devices
- SPI NOR flash interface
- SPI NAND flash interface
- eMMC v5.1 interface
- I2C to control peripheral devices
- General Purpose Input/Output
- PWM (Pulse Width Modulation)
- Audio PCM interface

- **Operating conditions**

- Logic voltage: 0.85V
- CPU voltage: 1.023V
- I/O voltage: 1.8V/3.3V
- DDR DRAM Interface: 1.2/1.5V/1.8V
- Clock source: 40MHz

- **Package**

- MFC VFBGA 16.85x16.85mm 570 balls
- Ball pitch: 0.65mm

## 1.2 Wireless Connectivity Features

### 1.2.1 Wi-Fi MAC

#### 1.2.1.1 Features

Wi-Fi MAC supports the following features:

- Support Dual band Dual Concurrent
- Support all data rates of 802.11a/b/g/n/ac/ax
- Support short GI and all data rates of 802.11n including MCS0 to MCS7
- Support 802.11ac MCS0 to MCS9
- Support 802.11ax MCS0 to MCS11
- AMPDU/AMSDU RX (de-aggregation) and TX (aggregation) support
- TX beamformer and RX beamformee
- TX rate adaptation
- TX power control
- Security
  - 64-bit WEP (WEP-40) and 128-bit WEP (WEP-104) encryption with hardware TKIP and CKIP processing
  - AES-CCMP hardware processing
  - GCMP hardware processing
- Management/control frame filtering

### 1.2.2 WLAN Baseband

#### 1.2.2.1 Features

Wi-Fi baseband supports the following features:

- Support Dual band Dual Concurrent
- 20/40/80/160 MHz channels
- HE MCS0-11 BW20/40/80/160MHz with Nss=1~4
- Short Guard Interval
- Space-time block code (STBC)
- Low Density Parity check (LDPC)
- Support digital pre-distortion to enhance PA performance
- Smoothing (channel estimation) extension to MIMO case
- Support radar detection
- Beamformer (explicit/implicit)
  - Eecoded BW20/40/80/160 up to 4x4 BF matrix apply
- Beamformee
  - Decoded BW20/40/80/160 up to 4x3 MU matrix feedback
- UL OFDMA / MU-MIMO
- DL OFDMA / MU-MIMO
- Max RU number in 2G band is 8
- Max RU number in 5/6G band is 16



### 1.3 Wired Ethernet Features

#### ● Frame Engine

- Packet DMA (PDMA)
  - 4 Tx descriptor and 4 Rx descriptor rings
  - Scatter/Gather DMA
  - Configurable 4/8/16/32 32-bit burst length and delayed interrupt
  - Support LRO and TSO
- QoS DMA (QDMA)
  - Supports 128 Tx physical queues and 4 sets of scheduler
  - Per Tx queue forward/drop packet accounting
  - Per Tx queue forward byte accounting
  - Supports Tx queue min/max rate control and SP/WFQ egress scheduler
  - Supports up to 1024 virtual queues for 8 sets of SFQ
- Packet Switch Engine (PSE)
  - Wire-speed NAT/NAPT routing
  - Egress rate limiting/shaping
  - IP/TCP/UDP checksum offload
  - IP/TCP/UDP checksum generation
  - VLAN & PPPoE header insertion
  - TCP segmentation offload
- Packet Process Engine (PPE)
  - IPv4 NAT/NAPT, IPv6 Routing and Tunnel IP (DS-Lite, 6RD, MAPE/T)
  - 1/2/4/8/16/32K session/flow
  - Flow offloading technology for flexible/high performance packet L3/L4 packet processing
  - Support NAT/NAPT wire-speed within 128 flows for any packet size

Note that PPE features mentioned above require software porting to function.

#### ● WiFi WARP

- Ethernet/WiFi offload, forwarding packet directly
- Dynamic buffer allocate and release

#### ● GigaMAC (GMAC)

- Support IEEE 802.3x full duplex flow control
- Support HSGMII interface
  - HSGMII supports 10/100/1000Mbps speed change through auto negotiation and configurable 2.5Gbps SerDes link

## 1.4 Main Features Summary

The following table covers the main features offered by MT7986A.

**Table 1-1 Main Features**

Feature	Description
<b>CPU</b>	<b>ARM CA53 (2.0GHz, Quad-core)</b>
I-Cache, D-Cache	32kB, 32kB per core
L2 Cache	512KB
Security	Support 2* 256-bit Multi-key on OTP efuse Support 64 versions OTP efuse for Anti-roll back
DRAM data width	16bit
DRAM type	DDR3-2133:256MB/512MB (2Gb/4Gb support) DDR4-3200:512MB/1GB/2GB (4Gb/8Gb/16Gb support) DDR4-2666:512MB/1GB/2GB (4Gb/8Gb/16Gb support)
WIFI	4x4 11ax 2.4GHz + 4x4 11ax 5GHz Integrated PA, LNA and TR-SW 20/40/80/160MHz bandwidth Support up to 1024QAM Support external LNA and PA support (option)
Ethernet	HSGMII x2
HNAT/HQoS	HQoS 128 queues, SFQ 1K queues HNAT (IPv4, IPv6 routing, DS-Lite, 6RD)
USB	USB3.0/2.0 x1, USB2.0 x1
PCIE	PCIe2.0 2lane HOST
SPI NAND Flash	ECC (BCH code) acceleration capable of 24-bit error correction (w/. ECC engine)
SPI Flash (NOR)	Max 52MHz data bit width x1/x2/x4 Support 4-byte address mode compatible with 3-byte address mode
eMMC	eMMC v5.1 @104MHz 1.8V
I2C	I2C x 1 Max 400kHz Support 7/10-bit addressing
SPI	SPI x 1 Support DMA and FIFO mode
UART	UART-Lite(2-pins) x 1 UART(4-pins) x2
PCM	Audio output PCM interface x1
Package	16.85 x 16.85 mm, MFC VFBGA-570B

MEDIATEK

MT7986A  
WiFi AP Router

2 Pin

---

## 2.1 Pin Sharing Schemes

Some pins are shared with GPIO to provide maximum flexibility for system designers. User can configure register to specify the pin function.

### 2.1.1 Pin share scheme

Table 2-1 Pin Share

Pin Name	Aux Func.0	Aux Func.1	Aux Func.2	Aux Func.3	Aux Func.4
SYS_WATCHDOG	GPIO0	SYS_WATCHDOG			
WF2G_LED	GPIO1	WF2G_LED			
WF5G_LED	GPIO2	WF5G_LED			
I2C_SCL	GPIO3	I2C_SCL	SGMII1_PHY_I2C_SCL	U3_PHY_I2C_SCL	
I2C_SDA	GPIO4	I2C_SDA	SGMII1_PHY_I2C_SDA	U3_PHY_I2C_SDA	
GPIO_0	GPIO5	PCIE_PHY_I2C_SCL	SGMII0_PHY_I2C_SCL		
GPIO_1	GPIO6	PCIE_PHY_I2C_SDA	SGMII0_PHY_I2C_SDA		
GPIO_2	GPIO7	DRV_VBUS	CONN0_UART_TXD0	UART1_RXD	
GPIO_3	GPIO8	DRV_VBUS_1P	CONN0_UART_TXD1	UART1_TXD	
GPIO_4	GPIO9	PCIE_CLK_REQ		UART1_CTS	
GPIO_5	GPIO10	PCIE_WAKE_N		UART1_RTS	
GPIO_6	GPIO11			SPIC_CLK	
GPIO_7	GPIO12			SPIC_MOSI	
GPIO_8	GPIO13			SPIC_MISO	
GPIO_9	GPIO14			SPIC_CS	
GPIO_10	GPIO15				
GPIO_11	GPIO16		CONN_ICE0_0		
GPIO_12	GPIO17		CONN_ICE0_1		
GPIO_13	GPIO18		CONN_ICE1_0		
GPIO_14	GPIO19		CONN_ICE1_1		
GPIO_15	GPIO20		PWM1		
PWM0	GPIO21	PWM0			
PWM1	GPIO22	PWM1	EMMC_RSTB	NET_WO0_UART_TXD	NET_WO1_UART_TXD
SPI0_CLK	GPIO23	SNFI_CLK	EMMC_DATA_0	SPIC_CLK	UART1_RXD
SPI0_MOSI	GPIO24	SNFI_MOSI	EMMC_DATA_1	SPIC_MOSI	UART1_TXD
SPI0_MISO	GPIO25	SNFI_MISO	EMMC_DATA_2	SPIC_MISO	UART1_CTS
SPI0_CS	GPIO26	SNFI_CS	EMMC_DATA_3	SPIC_CS	UART1_RTS
SPI0_HOLD	GPIO27	SNFI_HOLD	EMMC_DATA_4		
SPI0_WP	GPIO28	SNFI_WP	EMMC_DATA_5		
SPI1_CLK	GPIO29	SPIC_CLK	EMMC_DATA_6	UART1_RXD	UART2_RXD
SPI1_MOSI	GPIO30	SPIC_MOSI	EMMC_DATA_7	UART1_TXD	UART2_TXD
SPI1_MISO	GPIO31	SPIC_MISO	EMMC_CMD	UART1_CTS	UART2_CTS
SPI1_CS	GPIO32	SPIC_CS	EMMC_CK	UART1_RTS	UART2_RTS
SPI2_CLK	GPIO33	SPI0_CLK		UART2_RXD	SPIC_CLK
SPI2_MOSI	GPIO34	SPI0_MOSI		UART2_TXD	SPIC_MOSI
SPI2_MISO	GPIO35	SPI0_MISO	UART1_RXD	UART2_CTS	SPIC_MISO
SPI2_CS	GPIO36	SPI0_CS	UART1_TXD	UART2_RTS	SPIC_CS

Pin Name	Aux Func.0	Aux Func.1	Aux Func.2	Aux Func.3	Aux Func.4
SPI2_HOLD	GPIO37	SPI0_HOLD	UART1_CTS		
SPI2_WP	GPIO38	SPI0_WP	UART1_RTS		
UART0_RXD	GPIO39	UART0_RXD			
UART0_TXD	GPIO40	UART0_TXD			
PCIE_PERESET_N	GPIO41	PCIE_PERESET_N			
UART1_RXD	GPIO42	UART1_RXD	UART_PTA_RXD		
UART1_TXD	GPIO43	UART1_TXD	UART_PTA_TXD		
UART1_CTS	GPIO44	UART1_CTS	EXT_IF0_0		
UART1_RTS	GPIO45	UART1_RTS	EXT_IF0_1		
UART2_RXD	GPIO46	UART2_RXD	EXT_IF0_2		
UART2_TXD	GPIO47	UART2_TXD	EXT_IF1_0		
UART2_CTS	GPIO48	UART2_CTS	EXT_IF1_1		
UART2_RTS	GPIO49	UART2_RTS	EXT_IF1_2		
EMMC_DATA_0	GPIO50	EMMC_DATA_0			
EMMC_DATA_1	GPIO51	EMMC_DATA_1			
EMMC_DATA_2	GPIO52	EMMC_DATA_2			
EMMC_DATA_3	GPIO53	EMMC_DATA_3			
EMMC_DATA_4	GPIO54	EMMC_DATA_4			
EMMC_DATA_5	GPIO55	EMMC_DATA_5			
EMMC_DATA_6	GPIO56	EMMC_DATA_6			
EMMC_DATA_7	GPIO57	EMMC_DATA_7			
EMMC_CMD	GPIO58	EMMC_CMD			
EMMC_CK	GPIO59	EMMC_CK			
EMMC_DSL	GPIO60	EMMC_DSL			
EMMC_RSTB	GPIO61	EMMC_RSTB			
PCM_DTX	GPIO62	PCM_DTX			
PCM_DRX	GPIO63	PCM_DRX			
PCM_CLK	GPIO64	PCM_CLK			
PCM_FS	GPIO65	PCM_FS			
MT7531_INT	GPIO66	MT7531_INT			
SMI_MDC	GPIO67	SMI_MDC			
SMI_MDIO	GPIO68	SMI_MDIO			
WF0_DIG_RESETB	GPIO69	WF0_DIG_RESETB			
WF0_CBA_RESETB	GPIO70	WF0_CBA_RESETB			
WF0_XO_REQ	GPIO71	WF0_XO_REQ			
WF0_TOP_CLK	GPIO72	WF0_TOP_CLK			
WF0_TOP_DATA	GPIO73	WF0_TOP_DATA			
WF0_HB1	GPIO74	WF0_HB1	WF0_HB1	WF0_MODE_SEL_1	
WF0_HB2	GPIO75	WF0_HB2	WF0_HB2	WF0_MODE_SEL_2	
WF0_HB3	GPIO76	WF0_HB3	WF0_HB3	WF0_XTAL_SEL_0	
WF0_HB4	GPIO77	WF0_HB4	WF0_HB4	WF0_XTAL_SEL_1	
WF0_HB0	GPIO78	WF0_O_HB0	WF0_O_HB0	WF0_MODE_SEL_0	
WF0_HB0_B	GPIO79	WF0_HB0_B	WF1_O_HB0		

Pin Name	Aux Func.0	Aux Func.1	Aux Func.2	Aux Func.3	Aux Func.4
WF0_HB5	GPIO80	WF0_HB5	WF1_HB1	WF0_XTAL_SEL_2	
WF0_HB6	GPIO81	WF0_HB6	WF1_HB2		
WF0_HB7	GPIO82	WF0_HB7	WF1_HB3		
WF0_HB8	GPIO83	WF0_HB8	WF1_HB4		
WF0_HB9	GPIO84	WF0_HB9	WF1_HB5		
WF0_HB10	GPIO85	WF0_HB10	WF1_HB6		
WF1_DIG_RESETB	GPIO86	WF1_DIG_RESETB			
WF1_CBA_RESETB	GPIO87	WF1_CBA_RESETB			
WF1_XO_REQ	GPIO88	WF1_XO_REQ			
WF1_TOP_CLK	GPIO89	WF1_TOP_CLK			
WF1_TOP_DATA	GPIO90	WF1_TOP_DATA			
WF1_HB1	GPIO91	WF1_HB1	WF1_MODE_SEL_1		
WF1_HB2	GPIO92	WF1_HB2	WF1_MODE_SEL_2		
WF1_HB3	GPIO93	WF1_HB3	WF1_XTAL_SEL_0		
WF1_HB4	GPIO94	WF1_HB4	WF1_XTAL_SEL_1		
WF1_HB0	GPIO95	WF1_O_HB0	WF1_MODE_SEL_0		
WF1_HB0_B	GPIO96	WF1_HB0_B			
WF1_HB5	GPIO97	WF1_HB5	WF1_XTAL_SEL_2		
WF1_HB6	GPIO98	WF1_HB6			
WF1_HB7	GPIO99	WF1_HB7			
WF1_HB8	GPIO100	WF1_HB8			

## 2.2 Strapping Options

**Table 2-2 Strapping**

Pin Name	Strapping Name	Description
{GPIO_1, GPIO_0}	Boot Mode	00 : SPI-NOR 01 : SPI-NAND 10 : EMMC 11 : SNAND(SNFI)
GPIO_3	A-Die Mode	0: Two A-Die
UART0_TXD	Second A-Die XTAL mode select	0 : XTAL mode 1 : Buffer mode
PWM0	A-Die Crystal	1 : 40MHz XTAL
SYS_WATCHDOG	CPU voltage select	1 : 1.023V

### 3 Electrical Characteristics

#### 3.1 Absolute Maximum Ratings

**Table 3-1 Absolute Maximum Ratings**

Symbol or Pin name	Description	Min.	Max.	Unit
DVDD_CORE	0.85V supply voltage	-0.3	0.935	V
DVDD_PROC_L	1.023V CPU supply voltage	-0.3	1.125	V
SG0_AVDD09_SSUSB SG1_AVDD09_SSUSB U3_AVDD09_SSUSB AVDD09_PCIE	0.9V supply voltage	-0.3	0.990	V
AFE0_AVDD12_WBG AFE1_AVDD12_WBG AVDD12_CKSQ U2_0_AVDD12_USB U2_1_AVDD12_USB	1.2V supply voltage	-0.3	1.320	V
AVDDQ_EMI0 AVDDQ_EMI0_CA	1.5V/1.2V supply voltage	-0.3 -0.3	1.575 1.320	V
DVDD18IO_LB DVDD18IO_LT DVDD18IO_RB_C0 DVDD18IO_RB_C1 DVDD18IO_RT_C0 DVDD18IO_RT_C2 DVDD18IO_WF0 DVDD18IO_WF1 AFE0_AVDD18_WBG AFE1_AVDD18_WBG AVDD18_CKSQ AVDD18_POR AVDD18_AP AVDD18_PLLGP AVDD18_EMI0 SG0_AVDD18_SSUSB SG1_AVDD18_SSUSB U2_0_AVDD18_USB U2_1_AVDD18_USB U3_AVDD18_SSUSB AVDD18_PCIE VQPS	1.8V supply voltage	-0.3	1.980	V
DVDD33IO_LB DVDD33IO_LT DVDD33IO_RB_C0 DVDD33IO_RB_C1 DVDD33IO_RT_C0 U2_0_AVDD33_USB U2_1_AVDD33_USB	3.3V supply voltage	-0.3	3.630	V



### 3.2 Recommended Operating Range

**Table 3-2 Recommended Operating Range**

Symbol or Pin name	Description	Min.	Typ.	Max.	Unit
DVDD_CORE	0.85V supply voltage	0.808	0.85	0.935	V
DVDD_PROC_L	1.023V CPU supply voltage	0.972	1.023	1.125	V
SG0_AVDD09_SSUSB SG1_AVDD09_SSUSB U3_AVDD09_SSUSB AVDD09_PCIE	0.9V supply voltage	0.855	0.9	0.945	V
AFE0_AVDD12_WBG AFE1_AVDD12_WBG AVDD12_CKSQ U2_0_AVDD12_USB U2_1_AVDD12_USB	1.2V supply voltage	1.140	1.2	1.260	V
AVDDQ_EMI0 AVDDQ_EMI0_CA	1.5V/1.2V supply voltage	1.425 1.140	1.5 1.2	1.575 1.260	V
DVDD18IO_LB DVDD18IO_LT DVDD18IO_RB_C0 DVDD18IO_RB_C1 DVDD18IO_RT_C0 DVDD18IO_RT_C2 DVDD18IO_WF0 DVDD18IO_WF1 AFE0_AVDD18_WBG AFE1_AVDD18_WBG AVDD18_CKSQ AVDD18_POR AVDD18_AP AVDD18_PLLGP AVDD18_EMI0 SG0_AVDD18_SSUSB SG1_AVDD18_SSUSB U2_0_AVDD18_USB U2_1_AVDD18_USB U3_AVDD18_SSUSB AVDD18_PCIE VQPS	1.8V supply voltage	1.710	1.8	1.890	V
DVDD33IO_LB DVDD33IO_LT DVDD33IO_RB_C0 DVDD33IO_RB_C1 DVDD33IO_RT_C0 U2_0_AVDD33_USB U2_1_AVDD33_USB	3.3V supply voltage	2.970	3.3	3.630	V
T_ambient	Ambient temperature	-10	-	70	°C

### 3.3 Thermal Characteristics

Thermal characteristics when stationary without an external heat sink in an air-conditioned environment.

**Table 3-3 Thermal Characteristics**

Symbol	Description	Performance	
		Typ	Unit
TJ	Maximum Junction Temperature (Plastic Package)	125	°C
θJA	Junction to ambient temperature thermal resistance[1] for JEDEC 4L PCB	10.6	°C/W
θJC	Junction to case temperature thermal resistance	3.4	°C/W
θJB	Junction to case temperature thermal resistance	4.57	°C/W
ψJt	Junction to the package thermal resistance for JEDEC 4L PCB	0.45	°C/W

Note: JEDEC 51-9 system FR4 PCB size: 101.5 x 114.5 mm (4"x4.5")

### 3.4 Current Consumption

Please reference to Application note.

### 3.5 Storage Conditions

The calculated shelf life in a sealed bag is 12 months if stored between 5 °C and 40 °C at less than 90% relative humidity (RH). After the bag is opened, devices that are subjected to solder reflow or other high temperature processes must be handled in the following manner:

- Mounted within 168 hours of factory conditions, i.e. < 30 °C at 60% RH.
- Storage humidity needs to maintained at < 10% RH.
- Baking is necessary if the customer exposes the component to air for over 168 hrs, baking conditions: 125 °C for 8 hrs.

## 3.6 AC Electrical Characteristics

### 3.6.1 UART Interface

MT7986A utilizes the Universal Asynchronous Receiver Transmitter (UART) interface as its host control interface. The electrical timing characteristic for the UART interface is illustrated below.

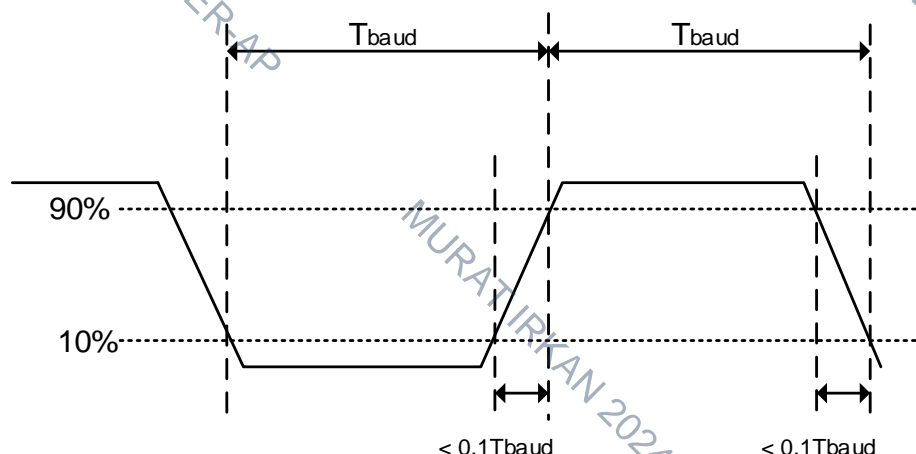


Figure 3-1 UART Timing

### 3.6.2 SPI Interface

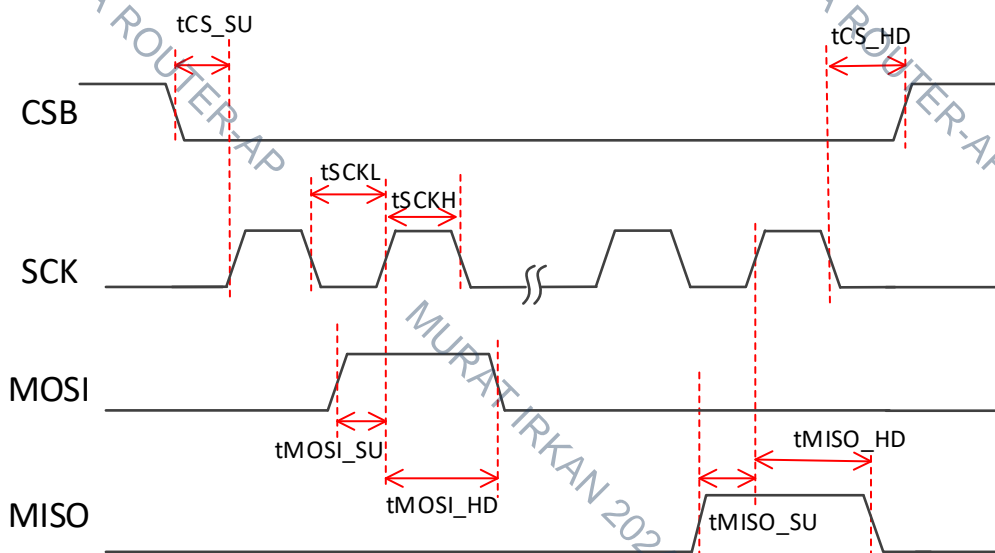


Figure 3-2 SPI Master Timing Diagrams

Table 3-4 SPI Master Electrical Specifications

Symbol	Description	Performance			Units
		Min.	Typ.	Max.	
fSCK	SPI Master SCK Clock frequency	-	-	52	MHz
tMOSI_SU	MOSI to SCK Rising setup Time	6.6	-	-	ns
tMOSI_HD	SCK Rising to MOSI hold Time	6.6	-	-	ns
tSCKL	SCK Low Pulse	7.2	-	-	ns
tSCKH	SCK High Pulse	7.2	-	-	ns
tCSB_SU <sup>1</sup>	CSB Falling to SCK Rising Setup Time	1.8	-	-	ns
tCSB_HD <sup>1</sup>	SCK Falling to CSB Rising Hold Time	1.8	-	-	ns
tMISO_SU <sup>2</sup>	MISO to SCK Rising Setup Time requirement	0	-	-	ns
tMISO_HD <sup>3</sup>	SCK Rising to MISO Hold Time requirement	0	-	-	ns

Notes:

1. In CS GPIO mode, SPI\_CS handled by SW. SW should pull down SPI\_CS pin before SPI starts transferring and pull up SPI\_CS pin when SPI completes the transaction. Based on the sequence above, the minimum specification of tCSB\_SU and tCSB\_HD time can be satisfied.
2. To achieve the min value of tMISO\_SU, the internal sample clock delay of SPI master should be adjusted.
3. MISO data valid time should be one cycle of fSCK.
4. For dual mode or quad mode, all the output data pins can refer to the MOSI timing parameters, and all the input data pins can refer to the MISO timing parameters.

### 3.6.3 SMI Interface

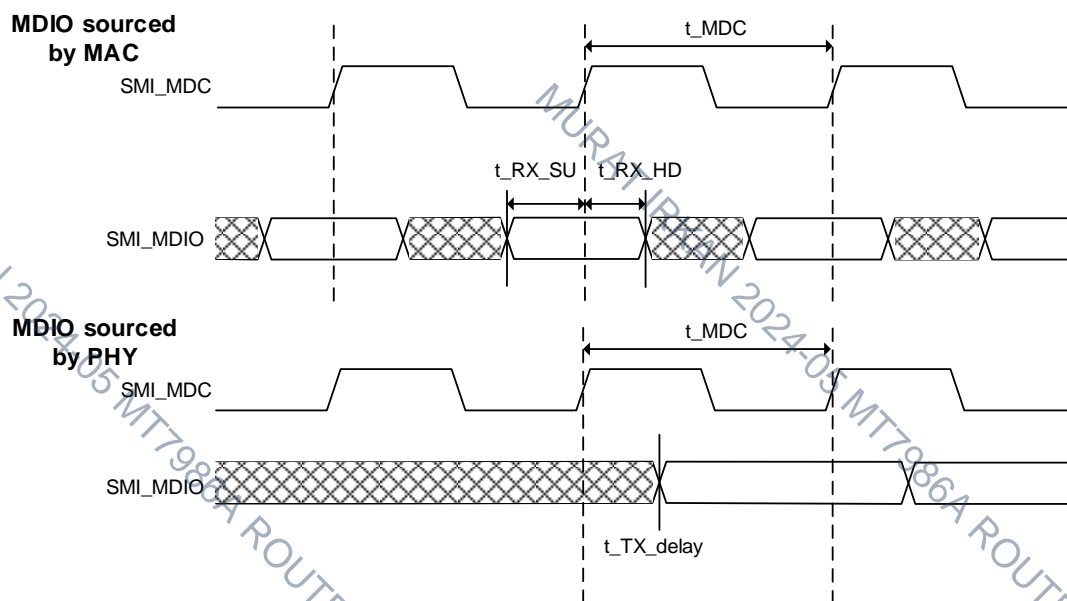


Figure 3-3 SMI MDIO Timing

Table 3-5 SMI Interface Diagram Key

Symbol	Description	Min	Max	Unit
t_TX_delay	Clock to output delay from the PHY	0	300	ns
t_RX_SU	Setup time referenced to the rising edge of SMI_MDC	10	-	ns
t_RX_HD	Hold time referenced to the rising edge of SMI_MDC	10	-	ns

Note: For 2.5 MHz SMI\_MDC

### 3.6.4 WRI Interface

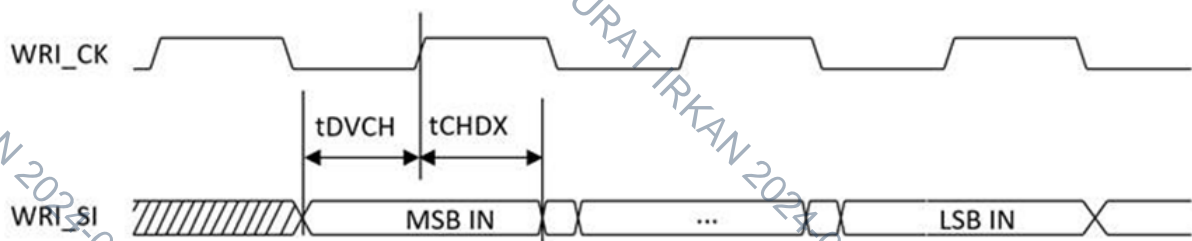


Figure 3-4 WRI Timing

Table 3-6 WRI Interface Diagram Key

Symbol	Description	Min	Max	Unit
tDVCH	Data in Setup Time	2	-	ns
tCHDX	Data in Hold Time	2	-	ns

### 3.6.5 I2C Interface

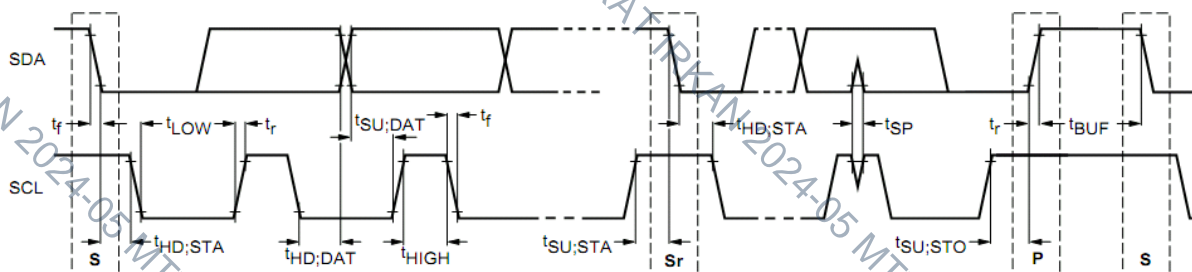


Figure 3-5 I2C Timing

Table 3-7 I2C Interface Diagram Key

Symbol	Description	Standard mode		Fast mode		Unit
		Min	Max	Min	Max	
fSCL	SCL clock frequency	0	100	0	400	kHz
tBUF	Bus free time between a STOP and START condition	4.7	-	1.3	-	us
tHD		-	-	-	-	us
tLOW	Hold time (repeated) START condition.	4.7	-	1.3	-	us
tHIGH	After this period, the first clock pulse is generated	4.0		0.6		us
tSU:STA	LOW period of the SCL clock	4.7	-	0.6	-	us
THD:DAT	HIGH period of the SCL clock	-	-	-	-	us
tSU:DAT	Setup time for a repeated START condition	250	-	100	-	ns
tr	Data hold time:	-	1000	20	300	ns
tf	Data setup time	-	300	20	300	ns
tSU:STO	Rise time of both SDA and SCL signals	4.0	-	0.6	-	us

## 3.7 DC Electrical Characteristics

### 3.7.1 3.3V IO

Table 3-8 3.3V IO Electrical Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
V <sub>IL</sub>	Input low voltage	-0.30	-	0.83	V
V <sub>IH</sub>	Input high voltage	2.06	-	3.63	V
V <sub>OL</sub>	Output low voltage	-0.30	-	0.41	V
V <sub>OH</sub>	Output high voltage	2.48	-	3.63	V
R <sub>PU</sub>	Input pull-up resistance	10	50	100	KΩ
R <sub>PD</sub>	Input pull-down resistance	5	7.5	10	KΩ

### 3.7.2 1.8V IO

Table 3-9 1.8V IO Electrical Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
V <sub>IL</sub>	Input low voltage	-0.30	-	0.63	V
V <sub>IH</sub>	Input high voltage	1.17	-	2.10	V

V <sub>OL</sub>	Output low voltage	-	-	0.45	V
V <sub>OH</sub>	Output high voltage	1.35	-	-	V
R <sub>PU</sub>	Input pull-up resistance	40	75	190	KΩ
R <sub>PD</sub>	Input pull-down resistance	40	75	190	KΩ